

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	DAE HEE LEE	07/15/2020
	YOUNG HOON KIM	07/15/2020
	YOUNG KYU JEONG	07/15/2020
RECEIVING PARTY DATA		
Name:	LG INNOTEK CO., LTD.	
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City:	SEOUL	
State/Country:	KOREA, REPUBLIC OF	
Postal Code:	07796	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	16977921	
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<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
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NAME OF SUBMITTER:	DANIEL Y.J. KIM	
SIGNATURE:	/Daniel Y.J. Kim/	
DATE SIGNED:	09/03/2020	
Total Attachments: 1		
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Docket No.:

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- | | |
|----------------------------|-----------|
| (1) <u>Dae Hee LEE</u> | (4) _____ |
| (2) <u>Young Hoon KIM</u> | (5) _____ |
| (3) <u>Young Kyu JEONG</u> | (6) _____ |

who have made a certain new and useful invention, hereby sell, assign and transfer unto

LG INNOTEK CO., LTD.
36, Magokjungang 10-ro, Gangseo-gu
Seoul, 07796 Republic of Korea

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

SEMICONDUCTOR DEVICE

(a) for which an application for United States Letters Patent was filed on _____, and identified by United States Serial No. _____; or

(b) for which an application for United States Letters Patent was executed on _____

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and/or that claim priority thereto and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof and/or that claim priority thereto, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

AND the undersigned hereby grants the firm of KED & ASSOCIATES, LLP the power to insert on this assignment any further identification that may be necessary or desirable in order to comply with the rules of any issuing authority, including the United States Patent and Trademark Office, for recordation of this document.

SIGNED on the dates indicated aside our signatures:

- INVENTORS
- | | |
|---------------------------|-----------------------|
| 1) <u>Dae Hee Lee</u> | Name: Dae Hee LEE |
| 2) <u>Young Hoon Kim</u> | Name: Young Hoon KIM |
| 3) <u>Young Kyu Jeong</u> | Name: Young Kyu JEONG |

DATE SIGNED
7.15.2020

DATE SIGNED
July 15, 2020

DATE SIGNED
7.15.2020